

Title (en)

METHOD AND DEVICE FOR DEPOSITING ELECTRONIC COMPONENTS ON A SUBSTRATE

Title (de)

VERFAHREN UND VORRICHTUNG ZUM ABLEGEN VON ELEKTRONISCHEN BAUTEILEN AUF EINEM SUBSTRAT

Title (fr)

PROCEDE ET DISPOSITIF POUR PLACER DES COMPOSANTS ELECTRONIQUES SUR UN SUPPORT

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2007033701A1] In a method for depositing electronic components (6) on a substrate (9), the component is transported initially by a primary tool (4) to an intermediate station (10) and from there by a secondary tool (12) to the substrate. The respective actual position of the chip before being picked up at the supply station (7) or at the intermediate station (10) and the position of the substrate at the depositing station (14) are determined by monitoring devices, in particular by cameras (1, 2, 11). Deviations in relation to a predetermined desired position on the substrate can be corrected by relative movement of the tools or possibly of the work stations. The advantage of this method is that any displacement errors when picking up a component can be eliminated by re-measurement at the intermediate station. Furthermore, the secondary tool (12), which oscillates between the intermediate station (10) and the depositing station (14), can be exposed to significantly different operating conditions, for example significantly higher temperatures, without the components at the supply station (17) being put at risk.

IPC 8 full level

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